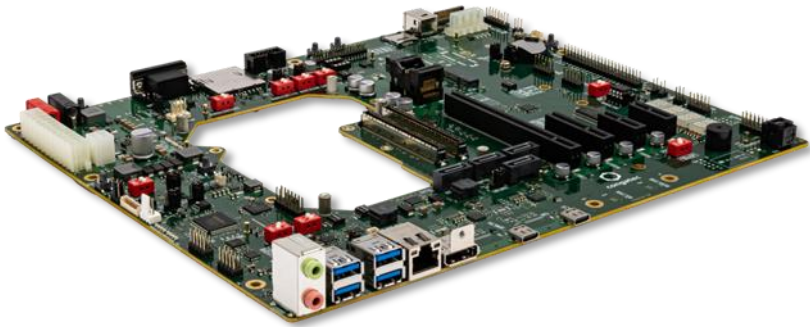


COM Express Type 6 Rev. 3.1 Evaluation Carrier Board

conga-TEVAL3/COMe 3.1



- Evaluation Carrier for COMe Type 6 modules
- Supports COMe Compact and Basic modules using connector Pinout Type 6
- Compliant to latest COMe Spec Rev. 3.1

Board Type	Evaluation Carrier Board for COM Express® Type 6 Modules Rev. 3.1
Internal IO	PCIe Gen4 x16 (PEG) PCIe Gen4 x4 2x PCIe Gen4 x1 M.2 Key B 2242/3042 (USB2.0 muxed, PCIe x1, SIM) M.2 Key E 2230 (USB2.0 muxed, PCIe x1) Dual USB2.0 header (muxed) USB Typ B (muxed) 3x SATA 6Gb/s SATA 6Gb/s with SATADOM Pin 7 LVDS (muxed with eDP) eDP (muxed with LVDS) VGA Dsub HDA/SoundWire header GSPI header SD Card socket (muxed with GPIOs) SPI boot flash socket Up to 4x COM headers CAN header LPC header Feature Connector ATX-4pin Power connector ATX-24pin Power connector Banana sockets for single power input
External IO	RJ45 2.5G Base-T 2x Dual USB Type A up to 10Gbps 2x USB4 Type C up to 20Gbps with Intel® JHL9040RIT Thunderbolt™ 4 Retimer DP++ HBR3 2x Audio Jack 3.5mm
Temperature Range	Operation -40°C to 85°C Storage -40°C to 85°C
Humidity	Operation 10% to 90% r. H. non cond. Storage 5% to 95% r. H. non cond.
Size	294 x 244 mm
Article	conga-TEVAL3/COMe 3.1 PN 065820

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